

## DC and RF Characterization Data Kurt Lesker PVD 75

**Note:** Please use this data as guidance, some further characterization might be required

<p><b>SnO<sub>2</sub></b> Film Thickness: <b>60 nm</b></p> <p>Baseline pressure: 2e-6 Torr RF Power: 300 W Deposition Time: 6 min Gas Pressure: Argon, 12.75 mTorr</p>	<p><b>Ti/Pt</b> Film Thickness: <b>100 nm</b></p> <p>Baseline pressure: 1.3e-6 Torr DC Power: 300 W Deposition Time: 2 min / 3 min Gas Pressure: Argon, 5 mTorr</p>
<p><b>Cr/Au</b> Film Thickness: <b>360 nm</b></p> <p>Baseline pressure: 1.3e-6 Torr DC Power: 300 W Deposition Time: 2 min / 6 min Gas Pressure: Argon, 5 mTorr</p>	<p><b>Ta</b> Film Thickness: <b>43 nm</b></p> <p>Baseline pressure: 3.0e-6 Torr DC Power: 200 W Deposition Time: 5 min Gas Pressure: Argon, 5 mTorr</p>
<p><b>Al</b> Film Thickness: <b>303 nm</b></p> <p>Baseline pressure: 1.5e-6 Torr DC Power: 300 W Deposition Time: 40 min Gas Pressure: Argon, 5 mTorr</p>	<p><b>Al</b> Film Thickness: <b>100 nm</b></p> <p>Baseline pressure: 1.5e-6 Torr DC Power: 500 W Deposition Time: 5 min Gas Pressure: Argon, 5 mTorr</p>
<p><b>Al (low stress)</b> Film Thickness: <b>170 nm</b></p> <p>Baseline pressure: 5e-6 Torr DC Power: 600 W Deposition Time: 20 min Gas Pressure: Argon, 25 mTorr</p>	<p><b>Sn</b> Film Thickness: <b>303 nm</b></p> <p>Baseline pressure: 1.5e-6 Torr DC Power: 300 W Deposition Time: 40 min Gas Pressure: Argon, 5 mTorr</p>
<p><b>Cu</b> Film Thickness: <b>50 nm</b></p> <p>Baseline pressure: 2.2e-6 Torr DC Power: 40 W Deposition Time: 20 min Gas Pressure: Argon, 5 mTorr</p>	<p><b>Ni</b> Film Thickness: <b>50 nm</b></p> <p>Baseline pressure: 2.3e-6 Torr DC Power: 300 W Deposition Time: 7 min Gas Pressure: Argon, 5 mTorr</p>

<p><b>Cr</b>  Film Thickness: <b>200 nm</b></p> <p>Baseline pressure: 2.1e-6 Torr  DC Power: 300 W  Deposition Time: 13 min  Gas Pressure: Argon, 5 mTorr</p>	<p><b>TiW</b>  Film Thickness: <b>90 nm</b></p> <p>Baseline pressure: 1.0e-7 Torr  DC Power: 300 W  Deposition Time: 20 min  Gas Pressure: Argon, 5 mTorr</p>
<p><b>Ti</b>  Film Thickness: <b>80 nm</b></p> <p>Baseline pressure: 5e-6 Torr  DC Power: 300 W  Deposition Time: 10 min  Gas Pressure: Argon, 5 mTorr</p>	<p><b>Fe<sub>2</sub>O<sub>3</sub></b>  Film Thickness: <b>47 nm</b></p> <p>Baseline pressure: 1.1e-6 Torr  RF Power: 200 W  Deposition Time: 15 min  Gas Pressure: Argon, 12 mTorr</p>
<p><b>SnO<sub>2</sub> (Reactive from the Sn target)</b>  Film Thickness: 160 nm</p> <p>Baseline pressure: 4e-7 Torr  DC Power: 75 W  Deposition Time: 20 min  Gas Pressure: Argon + O<sub>2</sub> 30% 10 mTorr</p>	